

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : **10/809,182** Confirmation No. **6820**
Applicant(s) : **UMENO, Kuniharu et al.**
Filed : **03/25/2004**
TC/A.U. : **1712**
Examiner : **Robert E. Sellers**
Title : **Resin Composition for Encapsulating Semiconductor Chip and
Semiconductor Device Therewith**

Docket No. : **033036.076**
Customer No. : **25461**

MAIL STOP AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450
Sir:

AMENDMENT

In response to the Office Action of April 16, 2007, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.